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# NC7SZ19

## TinyLogic® UHS 1-of-2 Decoder / Demultiplexer

### Features

- Ultra-High Speed:  $t_{PD}$  2.7ns Typical at 5V  $V_{CC}$
- Broad  $V_{CC}$  Operating Range: 1.65V to 5.55V
- Power Down High Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages

### Description

The NC7SZ19 is a 1-of-2 decoder with a common output enable. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad  $V_{CC}$  operating range. The device is specified to operate over the 1.65V to 5.5V  $V_{CC}$  range. The inputs and outputs are high impedance when  $V_{CC}$  is 0V. Inputs tolerate voltages up to 5.5V independent of  $V_{CC}$  operating voltage.

### Ordering Information

Part Number	Top Mark	Package	Packing Method
NC7SZ19P6X	Z19	6-Lead SC70, EIAJ SC88 1.25mm Wide	3000 Units on Tape & Reel
NC7SZ19L6X	B4	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7SZ19FHX	B4	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

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MicroPak™ is a trademark of Fairchild Semiconductor Corporation.

## Pin Configurations

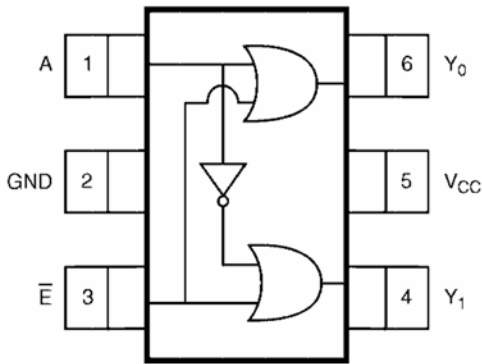


Figure 1. SC70 (Top View)

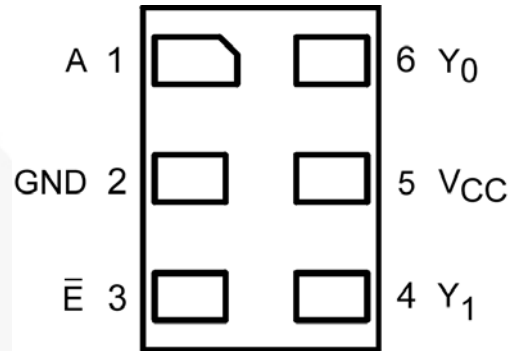


Figure 2. MicroPak™ (Top Through View)

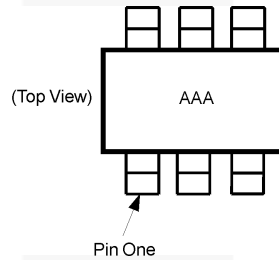


Figure 3. Pin 1 Orientation

### Notes:

1. AAA represents product code top mark (see *Ordering Information*).
2. Orientation of top mark determines pin one location.
3. Reading the top mark left to right, pin one is the lower left pin.

## Pin Definitions

Pin # SC70	Pin # MicroPak™	Name	Description
1	1	A	Decoder Address / Demultiplexer Select
2	2	GND	Ground
3	3	/E	Decoder Output Enable / Demultiplexer Data
4	4	Y <sub>1</sub>	Output
5	5	V <sub>CC</sub>	Supply Voltage
6	6	Y <sub>0</sub>	Output

## Function Table

Inputs		Output	
A	/E	Y <sub>0</sub> = A + /E	Y <sub>1</sub> = /A + /E
L	L	L	H
H	L	H	L
X	H	H	H

H = HIGH Logic Level

L = LOW Logic Level

X = Don't Care

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
$V_{CC}$	Supply Voltage		-0.5	7.0	V
$V_{IN}$	DC Input Voltage		-0.5	7.0	V
$V_{OUT}$	DC Output Voltage		-0.5	7.0	V
$I_{IK}$	DC Input Diode Current	$V_{IN} < -0.5V$		-50	mA
$I_{OK}$	DC Output Diode Current	$V_{IN} < -0.5V$		-50	mA
$I_{OUT}$	DC Output Current			±50	mA
$I_{CC}$ or $I_{GND}$	DC $V_{CC}$ or Ground Current			±100	mA
$T_{STG}$	Storage Temperature Range		-65	+150	°C
$T_J$	Junction Temperature Under Bias			+150	°C
$T_L$	Junction Lead Temperature (Soldering, 10 Seconds)			+260	°C
$P_D$	Power Dissipation at +85°C	SC70-6		180	mW
		MicroPak™-6		130	
		MicroPak2™-6		120	
ESD	Human Body Model, JEDEC:JESD22-A114			4000	V
	Charge Device Model, JEDEC:JESD22-C101			2000	

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
$V_{CC}$	Supply Voltage Operating		1.65	5.50	V
	Supply Voltage Data Retention		1.5	5.5	
$V_{IN}$	Input Voltage		0	5.5	V
$V_{OUT}$	Output Voltage		0	$V_{CC}$	V
$t_r, t_f$	Input Rise and Fall Times	$V_{CC}$ at 1.8V, ±0.15V, 2.5V ± 0.2V	0	20	ns/V
		$V_{CC}$ at 3.3V ± 0.3V	0	10	
		$V_{CC}$ at 5.0V ± 0.5V	0	5	
$T_A$	Operating Temperature		-40	+85	°C
$\theta_{JA}$	Thermal Resistance	SC70-6		425	°C/W
		MicroPak™-6		500	
		MicroPak2™-6		560	

### DC Electrical Characteristics

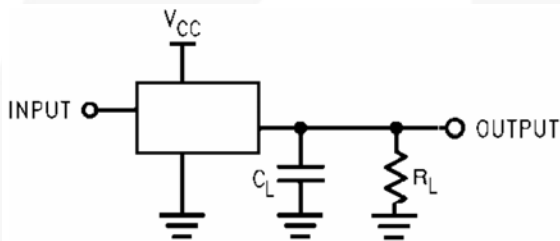
Symbol	Parameter	V <sub>CC</sub>	Condition	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40 to +85°C		Unit	
				Min.	Typ.	Max.	Min.	Max.		
V <sub>IH</sub>	HIGH Level Input Voltage	1.65		0.75V <sub>CC</sub>			0.75V <sub>CC</sub>		V	
		2.30 to 5.50		0.70V <sub>CC</sub>			0.70V <sub>CC</sub>			
V <sub>IL</sub>	LOW Level Input Voltage	1.65				0.25V <sub>CC</sub>		0.25V <sub>CC</sub>	V	
		2.30 to 5.50				0.30V <sub>CC</sub>		0.30V <sub>CC</sub>		
V <sub>OH</sub>	HIGH Level Output Voltage	1.65	V <sub>IN</sub> =V <sub>IH</sub> , or V <sub>OL</sub> , I <sub>OH</sub> =-100μA	1.55	1.65		1.55		V	
		2.30		2.20	2.30		2.20			
		3.00		2.90	3.00		2.90			
		4.50		4.40	4.50		4.40			
		1.65	I <sub>OH</sub> =-4mA	1.29	1.52		1.29			
		2.30		I <sub>OH</sub> =-8mA	1.90	2.15		1.90		
		3.00		I <sub>OH</sub> =-16mA	2.40	2.80		2.40		
		3.00		I <sub>OH</sub> =-24mA	2.30	3.68		2.30		
4.50	I <sub>OH</sub> =-32mA	3.80	4.20		3.80					
V <sub>OL</sub>	LOW Level Output Voltage	1.65	V <sub>IN</sub> =V <sub>IL</sub> , or, V <sub>IH</sub> , I <sub>OL</sub> =100μA		0.00	0.10		0.10	V	
		2.30			0.00	0.10		0.10		
		3.00			0.00	0.10		0.10		
		4.50			0.00	0.10		0.10		
		1.65	I <sub>OL</sub> =4mA		0.08	0.24		0.24		
		2.30		I <sub>OL</sub> =8mA		0.10	0.30			0.30
		3.00		I <sub>OL</sub> =16mA		0.15	0.40			0.40
		3.00		I <sub>OL</sub> =24mA		0.22	0.55			0.55
		4.50		I <sub>OL</sub> =32mA		0.22	0.55			0.55
I <sub>IN</sub>	Input Leakage Current	0 to 5.5	V <sub>IN</sub> =5.5V, GND			±0.1		±1.0	μA	
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> =5.5V			1		10	μA	
I <sub>CC</sub>	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> =5.5V, GND			1		10	μA	

### AC Electrical Characteristics

Symbol	Parameter	V <sub>CC</sub>	Condition	T <sub>A</sub> =+25°C			T <sub>A</sub> =-40 to +85°C		Unit	Figure
				Min.	Typ.	Max.	Min.	Max.		
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay A or /E to Output	1.80 ± 0.15	C <sub>L</sub> =15pF, R <sub>L</sub> =1MΩ,	2.5	5.9	10.5	2.5	11.0	ns	Figure 5 Figure 6
		2.50 ± 0.20		1.2	3.5	6.0	1.2	6.4		
		3.30 ± 0.30		0.8	2.7	4.1	0.8	4.5		
		5.00 ± 0.50		0.5	2.1	3.2	0.5	3.5		
		3.30 ± 0.30	C <sub>L</sub> =50pF, R <sub>L</sub> =500Ω,	1.2	3.2	5.1	1.2	5.4		
		5.00 ± 0.50		0.8	2.7	4.0	0.8	4.3		
C <sub>IN</sub>	Input Capacitance	0			2.3				pF	
C <sub>PD</sub>	Power Dissipation Capacitance <sup>(4)</sup>	3.30			10.5				pF	Figure 5
		5.00			12.8					

**Note:**

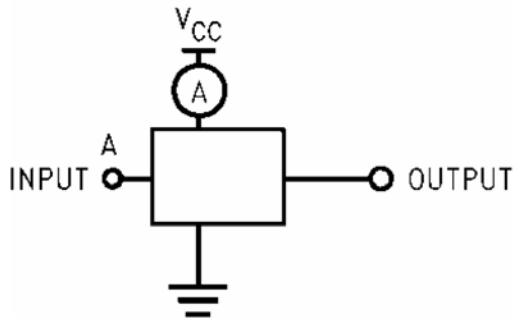
- C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub>=(C<sub>PD</sub>)(V<sub>CC</sub>)(f<sub>IN</sub>)+(I<sub>CC</sub>static).



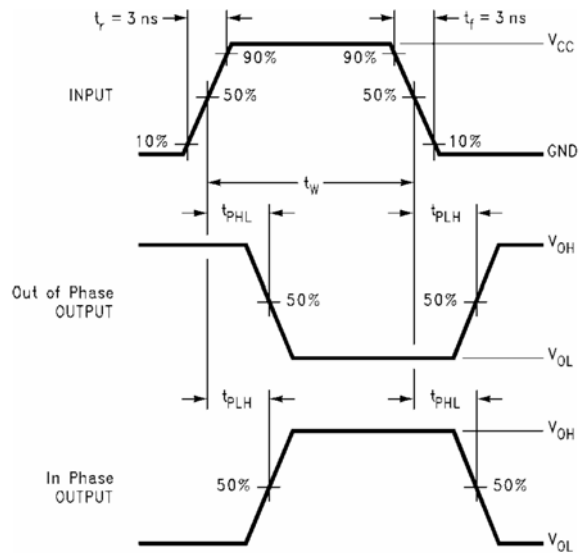
**Notes:**

- C<sub>L</sub> includes load and stray capacitance.
- Input PRR = 1.0MHz, t<sub>w</sub> = 500ns.

**Figure 4. AC Test Circuit**



**Figure 5. I<sub>CCD</sub> Test Circuit**

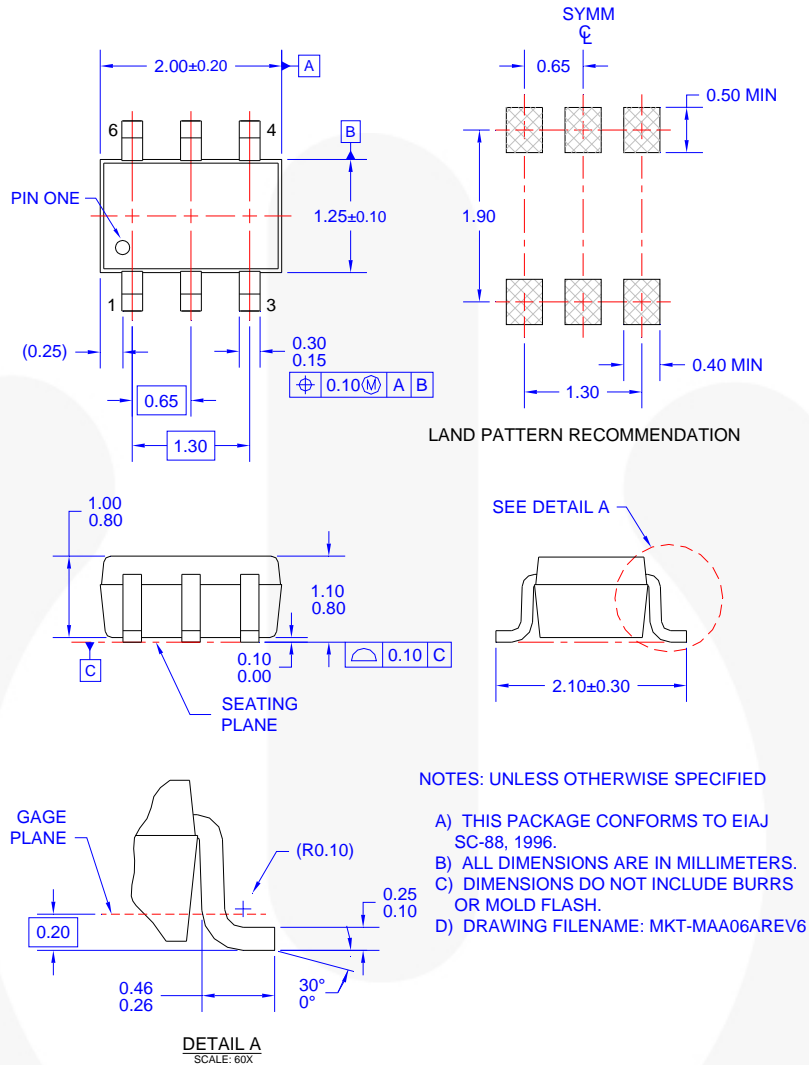


**Figure 6. AC Waveforms**

**Note:**

- Input=AC Waveform; t<sub>r</sub>=t<sub>f</sub>=1.8ns.
- PRR=10MHz; Duty Cycle=50%.
- /E Input=GND.

## Physical Dimensions



**Figure 7. 6-Lead, SC70, EIAJ SC88, 1.25mm Wide**

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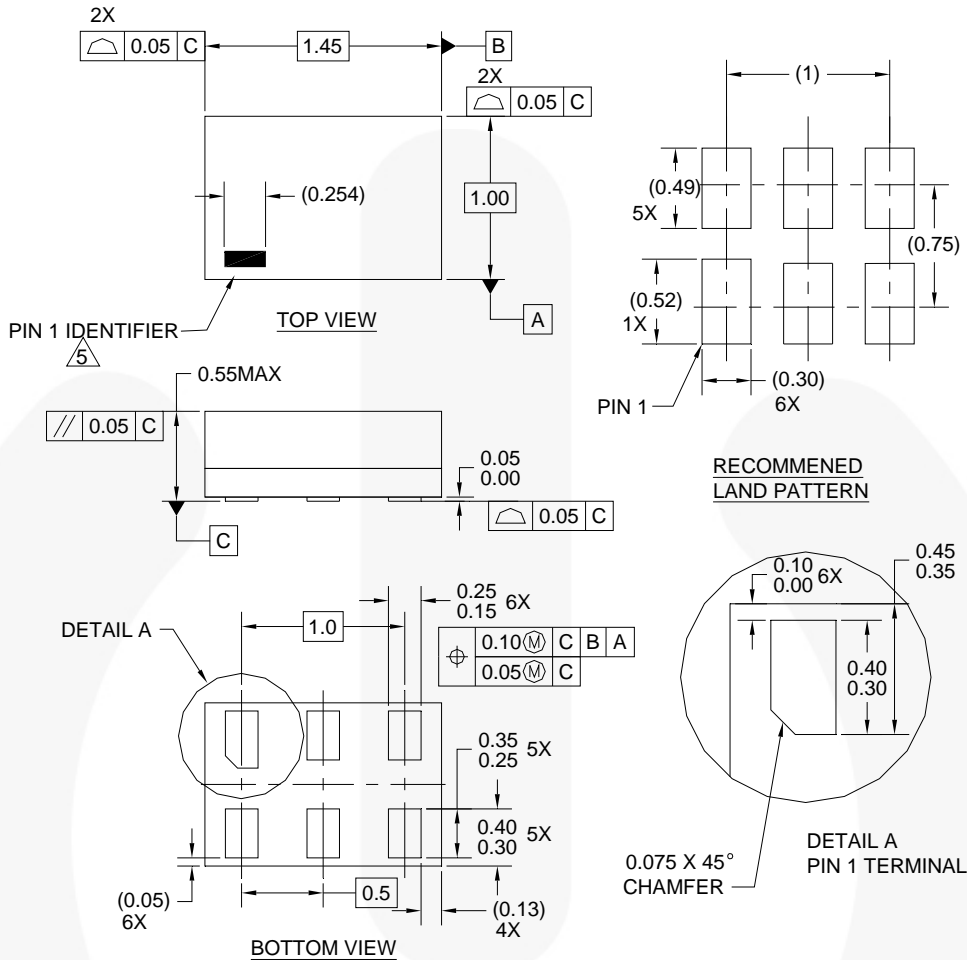
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## Tape and Reel Specification

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[http://www.fairchildsemi.com/products/analog/pdf/sc70-6\\_tr.pdf](http://www.fairchildsemi.com/products/analog/pdf/sc70-6_tr.pdf)

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
P6X	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

## Physical Dimensions



**Notes:**

1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994
4. FILENAME AND REVISION: MAC06AREV4
5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

**Figure 8. 6-Lead, MicroPak™, 1.0mm Wide**

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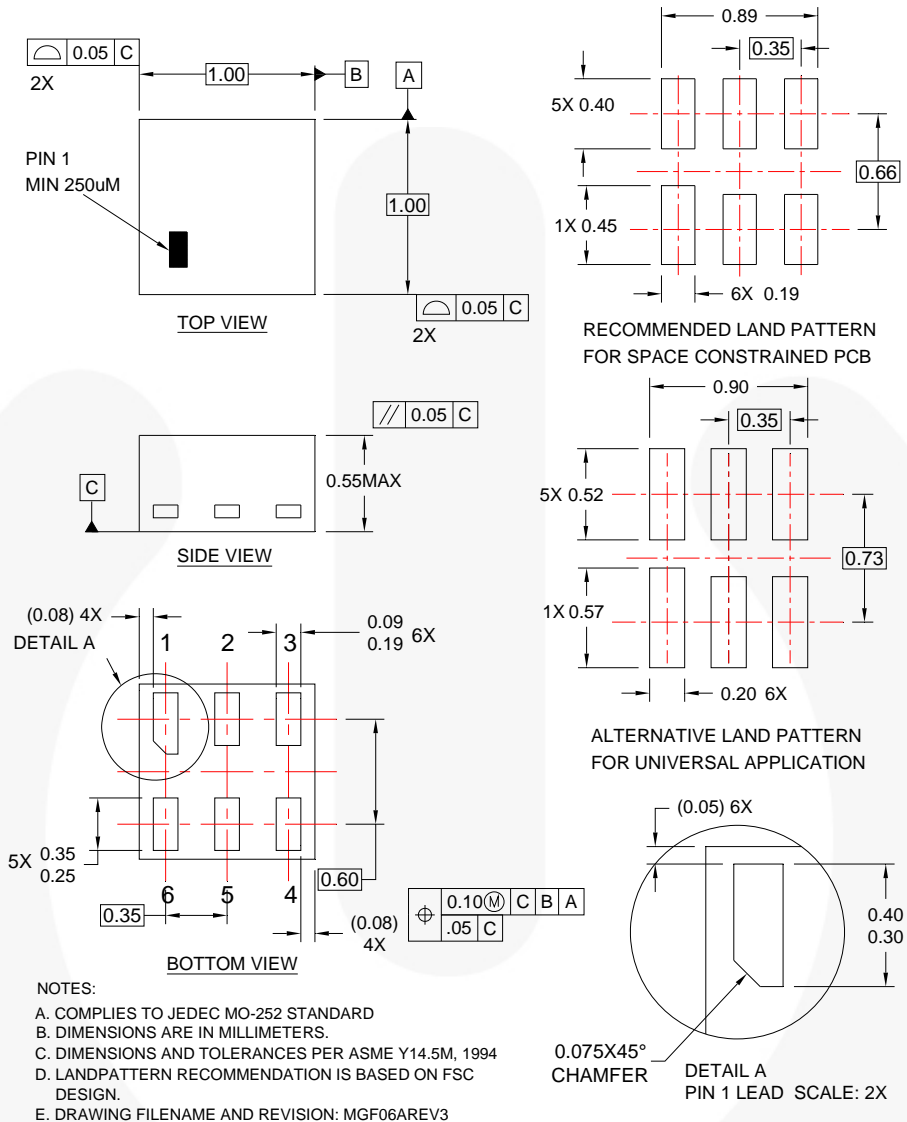
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[http://www.fairchildsemi.com/products/logic/pdf/micropak\\_tr.pdf](http://www.fairchildsemi.com/products/logic/pdf/micropak_tr.pdf).

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
L6X	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed



## Physical Dimensions



**Figure 9. 6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch**

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[http://www.fairchildsemi.com/packaging/MicroPAK2\\_6L\\_tr.pdf](http://www.fairchildsemi.com/packaging/MicroPAK2_6L_tr.pdf)

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
FHX	Leader (Start End)	125 (Typical)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed



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| CorePLUS™                | Green FPST™ e-Series™  | QFET®                               | TinyBuck™                              |
| CorePOWER™               | Gmax™                  | QS™                                 | TinyCalc™                              |
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| FACT Quiet Series™       | mWSaver™               | SuperSOT™-6                         | UniFET™                                |
| FACT®                    | OptoHit™               | SuperSOT™-8                         | Vcx™                                   |
| FAST®                    | OPTOLOGIC®             | SupreMOS®                           | VisualMax™                             |
| FastvCore™               | OPTOPLANAR®            | SynCFET™                            | XST™                                   |
| FETBench™                | ™                      | Syn-Lock™                           |  |
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**Definition of Terms**

Datasheet Identification	Product Status	Definition
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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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